

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claim 1 (currently amended): A digital camera, comprising:

an image sensor module, comprising a camera lens with a non-spherical surface and a planar surface, an infrared film, and an image sensor for transforming optical signals to analog signals, wherein the camera lens has a mounting part, the infrared film is plated on the planar surface of the camera lens, and the camera lens is spaced apart from the image sensor;

a Digital Signal Processor (DSP) for transforming analog signals to digital signals;

a Microprogrammed Control Unit (MCU) for processing the digital signals out from the DSP;

a dynamic random access memory (DRAM) for storing data;

an output apparatus; and

a circuitry for connecting the image sensor module, the DSP, the MCU, the DRAM and the output apparatus together.

Claims 2-6 (canceled)

Claim 7 (currently amended): ~~The digital camera as claimed in claim 1,~~  
wherein A digital camera, comprising:

an image sensor module, comprising a camera lens with a

non-spherical surface and a planar surface, and an image sensor for transforming optical signals to analog signals, wherein the camera lens is spaced apart from the image sensor, and the camera lens is fixed to the image sensor by hot mold glue;

a Digital Signal Processor (DSP) for transforming analog signals to digital signals;

a Microprogrammed Control Unit (MCU) for processing the digital signals out from the DSP;

a dynamic random access memory (DRAM) for storing data;

an output apparatus; and

a circuitry for connecting the image sensor module, the DSP, the MCU, the DRAM and the output apparatus together.

Claim 8 (original): The digital camera as claimed in claim 7, wherein the hot mold glue is 353ND epoxy.

Claims 9-11 (canceled)